

SMAK Plastic-Encapsulate Diodes

Schottky Rectifier

Features

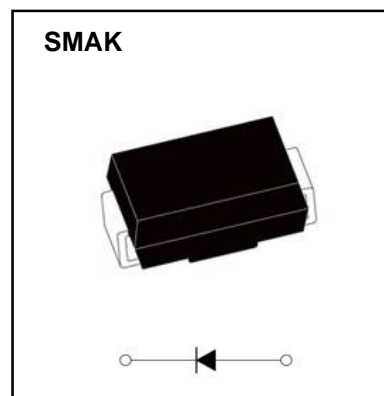
- I_o 1A
- V_{RRM} 20V-200V
- High surge current capability
- Polarity: Color band denotes cathode

Applications

- Rectifier

Marking

- SK1X
- X : From 2 To 20



Limiting Values (Absolute Maximum Rating)

Item	Symbol	Unit	Test Conditions	SK														
				12	13	14	15	16	18	110	115	120						
Repetitive Peak Reverse Voltage	V_{RRM}	V		20	30	40	50	60	80	100	150	200						
Maximum RMS Voltage	V_{RMS}	V		14	21	28	35	42	56	70	105	140						
Average Forward Current	$I_{F(AV)}$	A	60HZ Half-sine wave, Resistance load, TL(Fig.1)	1.0														
Surge(Non-repetitive)Forward Current	I_{FSM}	A	60Hz Half-sine wave , 1 cycle , $T_a = 25^\circ\text{C}$	30														
Junction Temperature	T_J	$^\circ\text{C}$		-55~+125					-55~+150									
Storage Temperature	T_{STG}	$^\circ\text{C}$		-55 ~ +150														

Electrical Characteristics ($T_a = 25^\circ\text{C}$ Unless otherwise specified)

Item	Symbol	Unit	Test Condition	SK									
				12	13	14	15	16	18	110	115	120	
Peak Forward Voltage	V_F	V	$I_F = 1.0\text{A}$	0.55			0.70			0.85		0.95	
Peak Reverse Current	I_{RRM1}	mA	$V_{RM} = V_{RRM}$	$T_a = 25^\circ\text{C}$				0.5				0.2	
	I_{RRM2}			10			5.0						
Thermal Resistance(Typical)	$R_{\theta J-A}$	$^\circ\text{C/W}$	Between junction and ambient	88 ¹⁾									
	$R_{\theta J-L}$		Between junction and terminal	28 ¹⁾									

Notes:

Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.2" x 0.2" (5.0 mm x 5.0 mm) copper pad areas

Typical Characteristics

FIG.1: FORWARD CURRENT DERATING CURVE

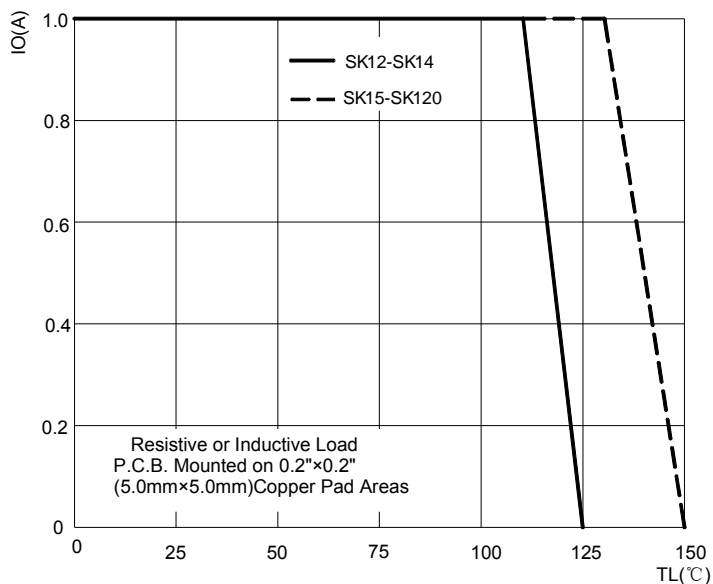


FIG2:Surge Forward Current Capadility

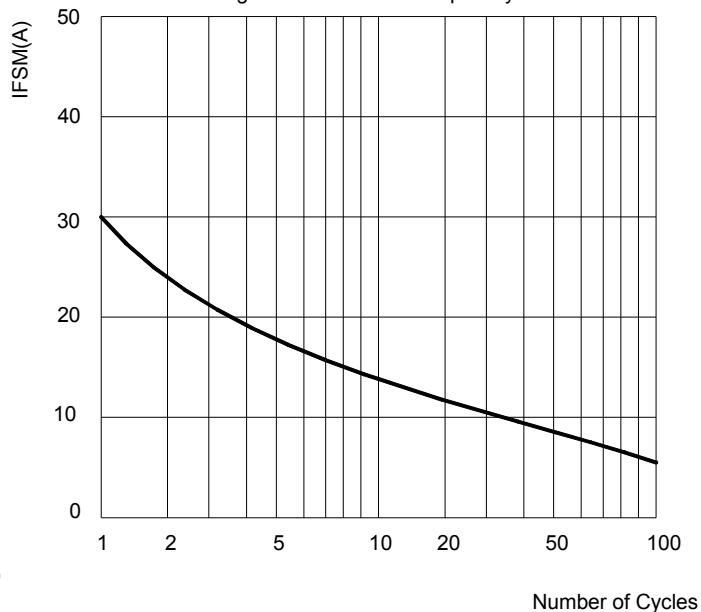


FIG.3: TYPICAL FORWARD CHARACTERISTICS

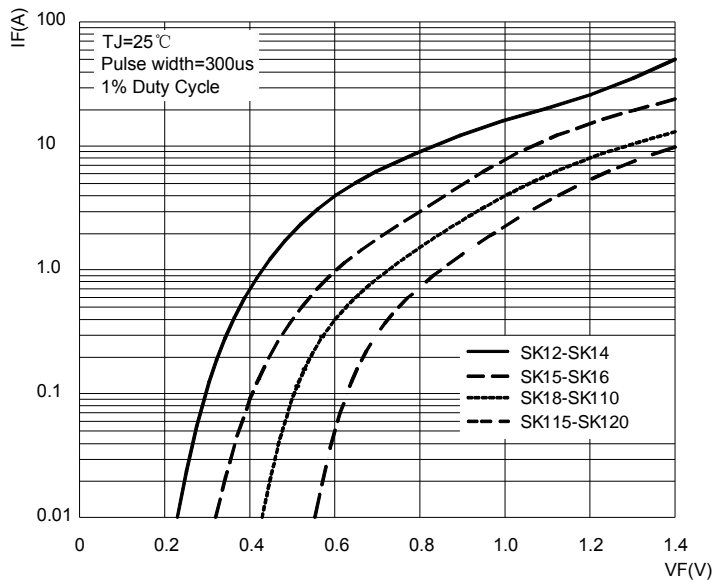
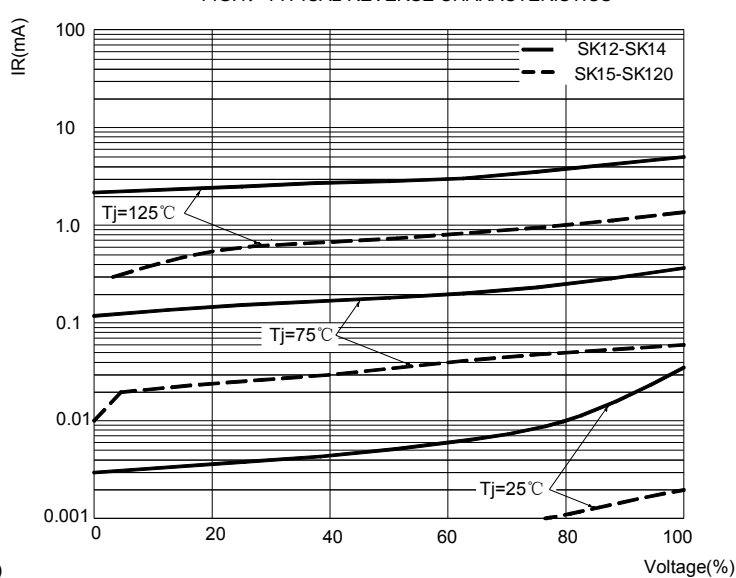
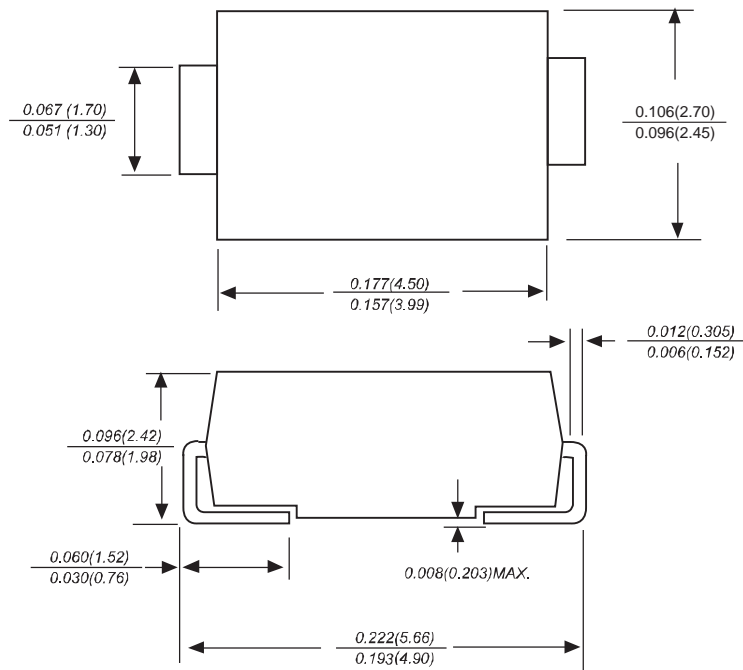


FIG.4: TYPICAL REVERSE CHARACTERISTICS

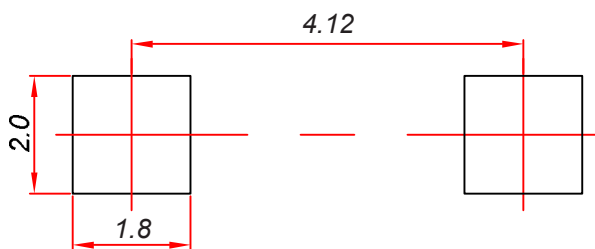


SMAK Package Outline Dimensions



Dimensions in inches and (millimeters)

SMAK Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05 \text{ mm}$.
3. The pad layout is for reference purposes only.

NOTICE

JSHD reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to any product herein. JSHD does not assume any liability arising out of the application or use of any product described herein.

Reel Taping Specifications For Surface Mount Devices- SMA

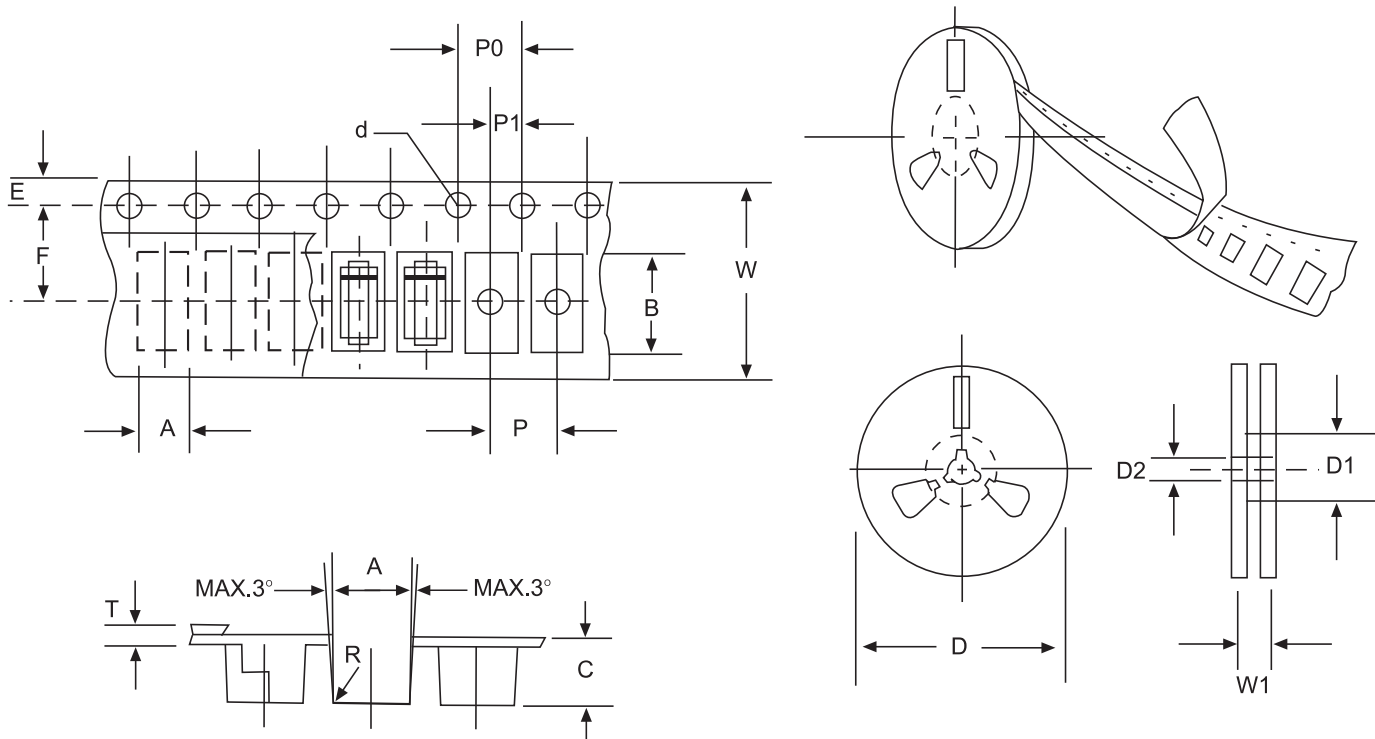


FIG:CONFIGURATION OF AXIAL TAPING

ITEM	SYMBOL	SMA mm(inch)
Carrier width	A	2.79±0.1(0.110±0.004)
Carrier length	B	5.33±0.1(0.210±0.004)
Carrier depth	C	2.36±0.1(0.093±0.004)
Sprocket hole	d	1.5±0.05(0.059±0.0002)
Reel outside diameter	D	330/178±2.0(13/7.0±0.79)
Reel inner diameter	D1	8.0±0.2(0.315±0.008)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Sprocket hole position	E	1.75±0.1(0.069±0.004)
Punch hole position	F	5.5±0.05(0.217±0.002)
Punch hole pitch	P	4.0±0.1(0.157±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Total tape thickness	T	0.28±0.02(0.011±0.0008)
Tape width	W	12.0±0.2(0.472±0.008)
Reel width	W1	16.8±2.0(0.661±0.079)

NOTE: Devices are packed in accordance with EIA standard RS-481-A and specification given above.